CRMPGL1025A

N-Channel 100V, 20mΩ Typ. Power MOSFET

Description

Features

• 100V, 7.5A

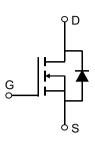
$$R_{DS(ON)}$$
 Typ = $20m\Omega$ @ V_{GS} = $10V$

$$R_{DS(ON)}$$
 Typ = 26m Ω @ V_{GS} = 4.5V

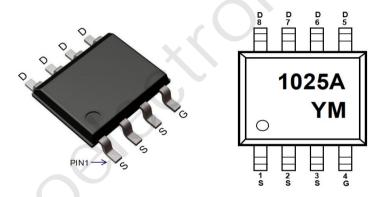
- Advanced Split Gate Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- Lead Free
- 100% UIS TESTED!
- 100% ΔVds TESTED!

Application

- Load Switch
- PWM Application
- Power Management







Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMPGL1025A	1025A	SOP-8	TAPING	13"	4000	40000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		100	V
V _{GS}	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	T _A = 25°C	7.5	Α
I _D		T _A = 100°C	4.5	Α
I _{DM}	Pulsed Drain Current (1)		30	Α
E _{AS}	Single Pulsed Avalanche Energy (2)		31	mJ
P_{D}	Power Dissipation	T _A = 25°C	2.5	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambien	nt ⁽³⁾	50	°C/W
T _J , T _{STG}	Junction & Storage Temperature Range		-55 to 150	°C

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Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Uni
Off Chara	acteristics					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 100V, V _{GS} = 0V	-	-	1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				6	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2	1.8	2.4	V
R _{DS(ON)} S	Static Drain-Source ON-Resistance ⁽⁴⁾	$V_{GS} = 10V, I_{D} = 5A$	-	20	26	mΩ
		$V_{GS} = 4.5V, I_{D} = 3A$	-	26	34	mΩ
Dynamic	Characteristics					
C _{iss}	Input Capacitance			660	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 25V,$ f = 1MHz	X - (375	-	pF
C_{rss}	Reverse Transfer Capacitance	1 - 11011 12		21	-	pF
Q_g	Total Gate Charge		<u>)</u> -	25	-	nC
Q_gs	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 50V, I_D = 7.5A$	-	6	-	nC
\mathbf{Q}_{gd}	Gate Drain("Miller") Charge	V _{DS} = 30 V, I _D = 7.3A	-	5	-	nC
Switchin	g Characteristics					
$t_{d(on)}$	Turn-On DelayTime		-	14	-	ns
t_r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 50V$	-	12	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	$I_{D} = 7.5A, R_{GEN} = 3\Omega$	-	23	-	ns
t_f	Turn-Off Fall Time		-	6	-	ns
Drain-So	urce Diode Characteristics and M	Max Ratings				
Is	I _S Maximum Continuous Drain to Source Diode Forward Current			-	7.5	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	30	Α
V_{SD}	Drain to Source Diode Forward Voltage V _{GS} = 0V, I _S = 7.5A		-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I - 7 EA - 4:/ 400A/	-	50	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 7.5A$, di/dt = 100A/us	-	90	-	nC

Notes:

- 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
- 2. E_{AS} condition: Starting T_J =25°C, V_{DD} =50V, V_G =10V, R_G =25ohm, L=0.5mH, I_{AS} =11A
- 3. $R_{\theta JA}$ is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB
- 4. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 0.5%.

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Test Circuit

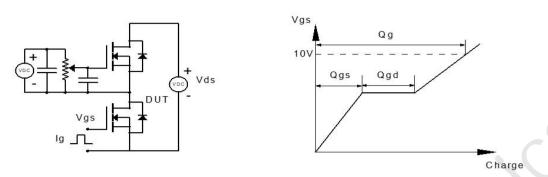


Figure 1: Gate Charge Test Circuit & Waveform

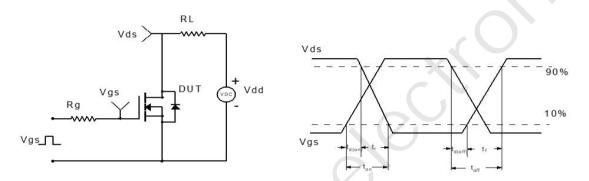


Figure 2: Resistive Switching Test Circuit & Waveform

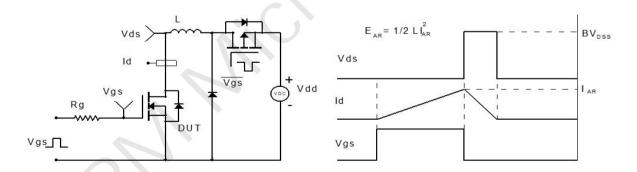


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

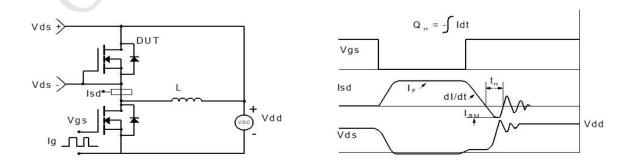
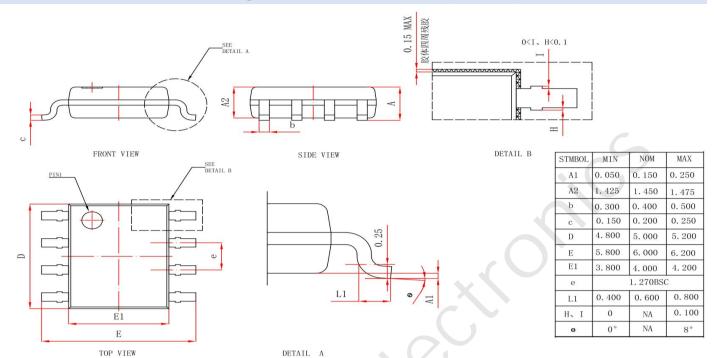


Figure 4: Diode Recovery Test Circuit & Waveform

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Package Mechanical Data(SOP-8)



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